VE320 – Summer 2021

Semiconductor Physics

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Chapter 10 Fundamentals of Metal-Oxide-Semiconductor Field Effect Transistors



Outline

- 10.1 The two-terminal MOS structure
- 10.2 Capacitance-voltage characteristics
- 10.3 Non-ideal effects
- 10.4 The basic MOSFET operation



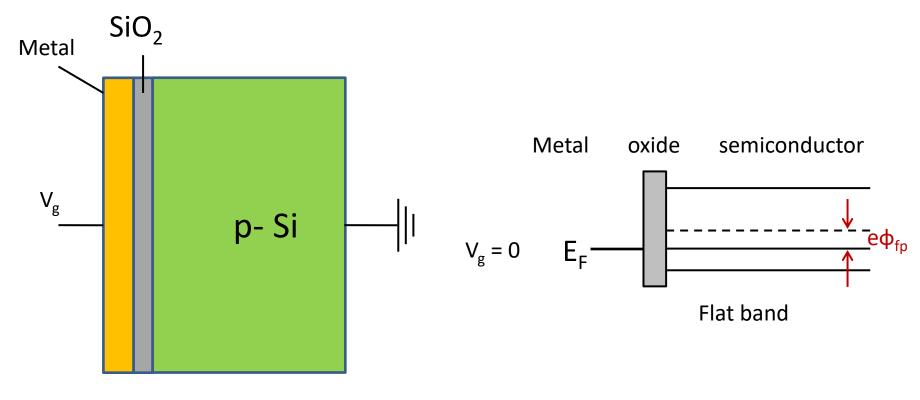
Outline

10.1 The two-terminal MOS structure

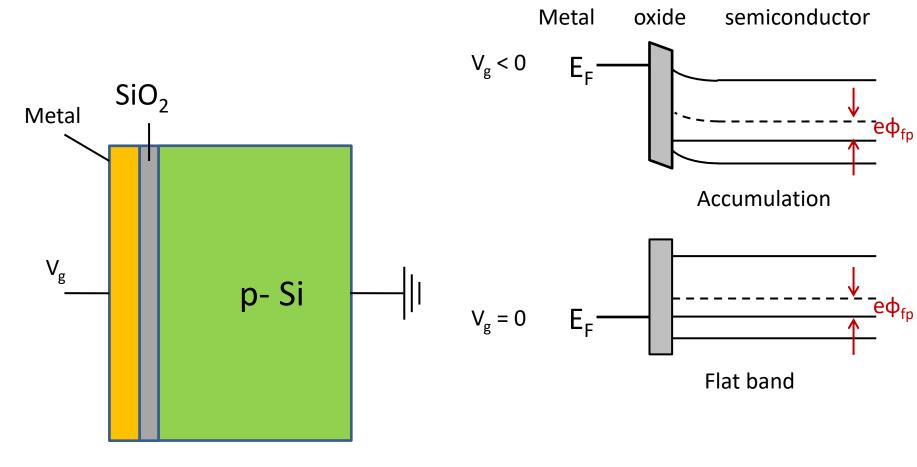
10.2 Capacitance-voltage characteristics

10.3 Non-ideal effects

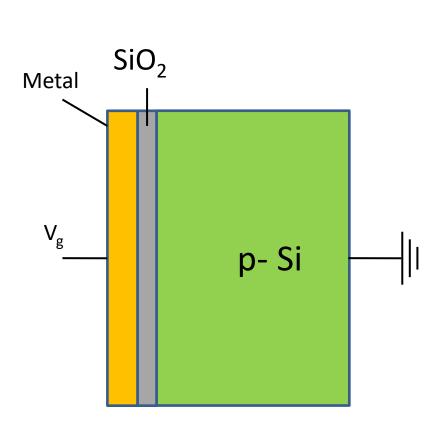
10.4 The basic MOSFET operation



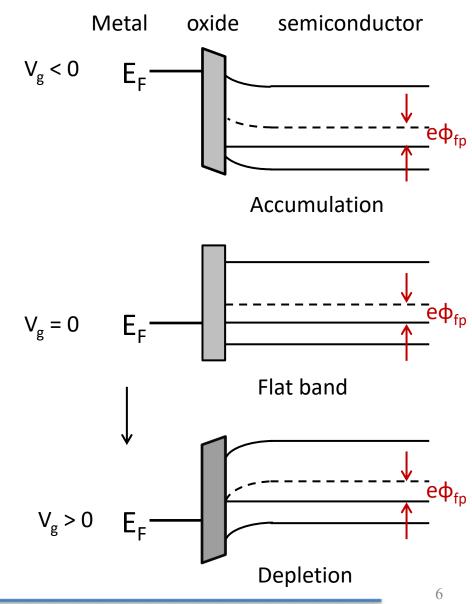
Metal-insulator-semiconductor (MIS)



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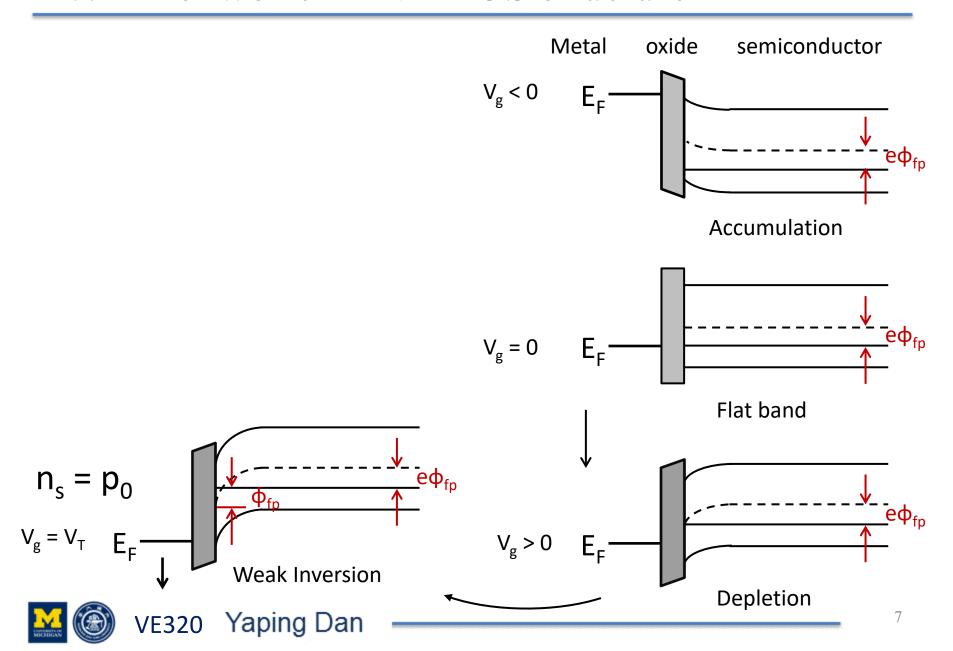


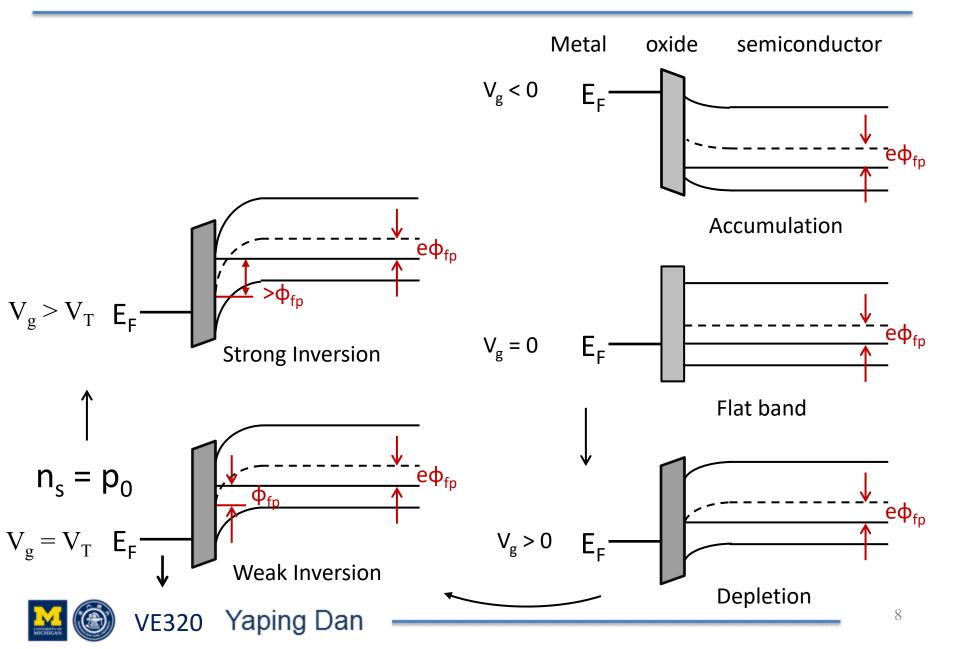
Metal-insulator-semiconductor (MIS)



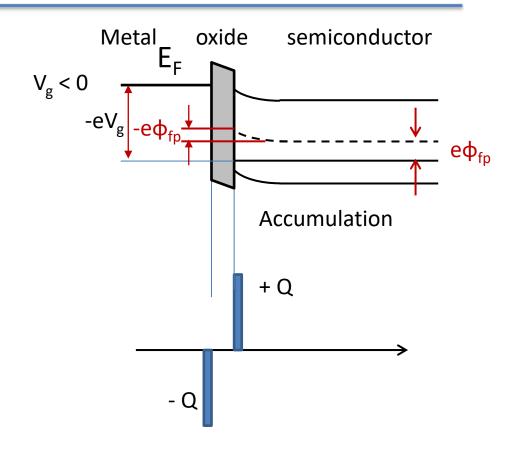




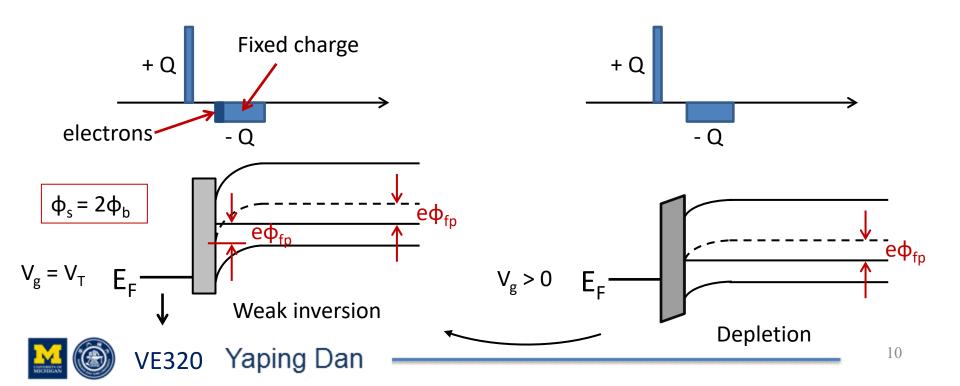




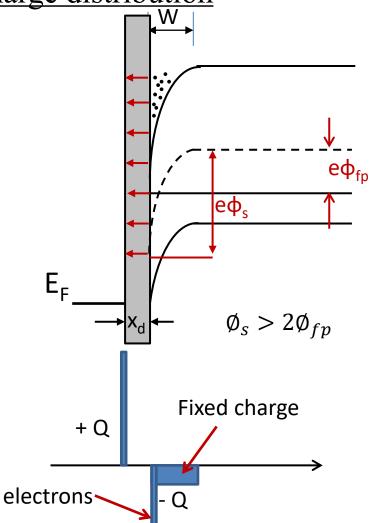
Charge distribution



Charge distribution

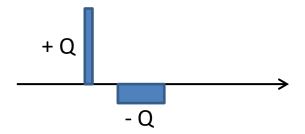


Charge distribution

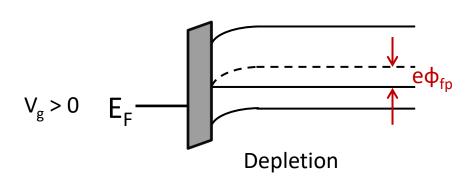




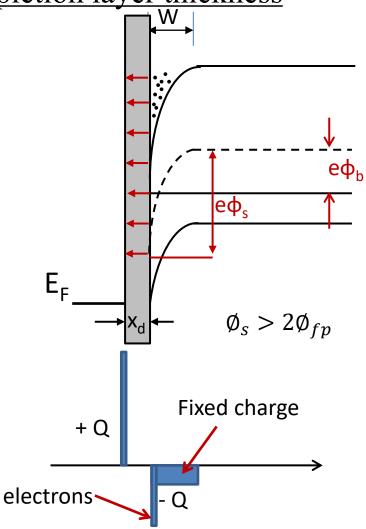
Depletion layer thickness



$$x_d = \left(\frac{2\epsilon_s \phi_s}{eN_a}\right)^{1/2}$$



Depletion layer thickness

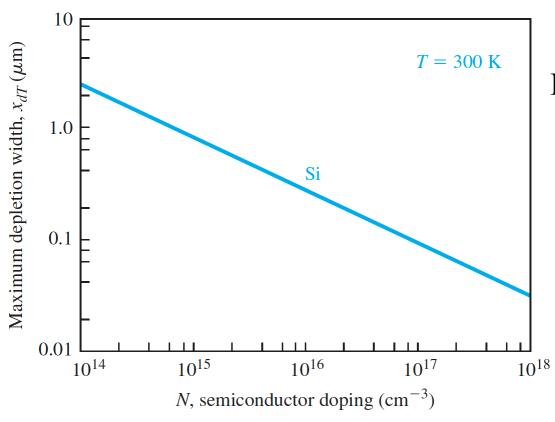


Maximum depletion layer

$$x_{dT} = \left(\frac{4\epsilon_s \phi_{fp}}{eN_a}\right)^{1/2}$$



Depletion layer thickness



Maximum depletion layer

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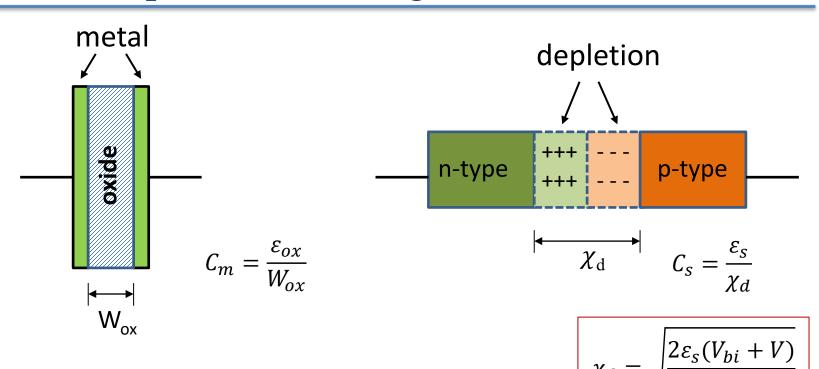
Outline

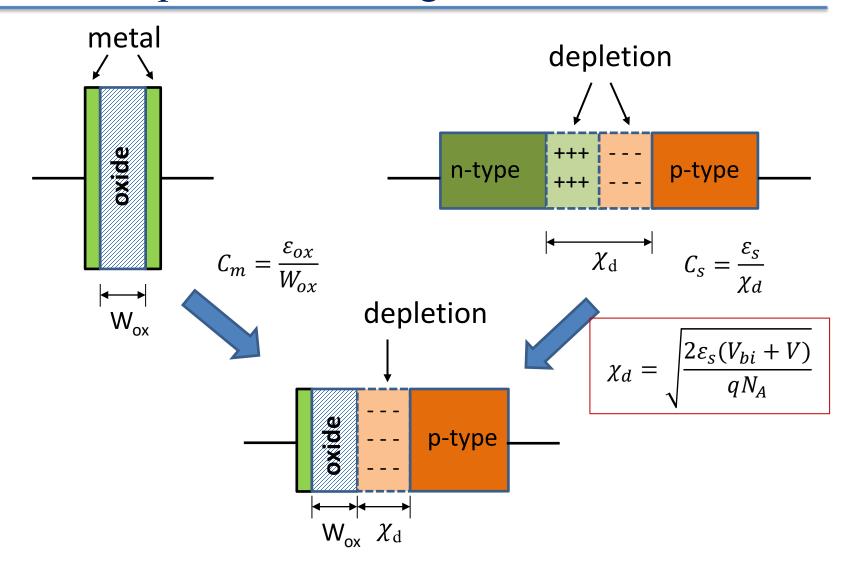
10.1 The two-terminal MOS structure

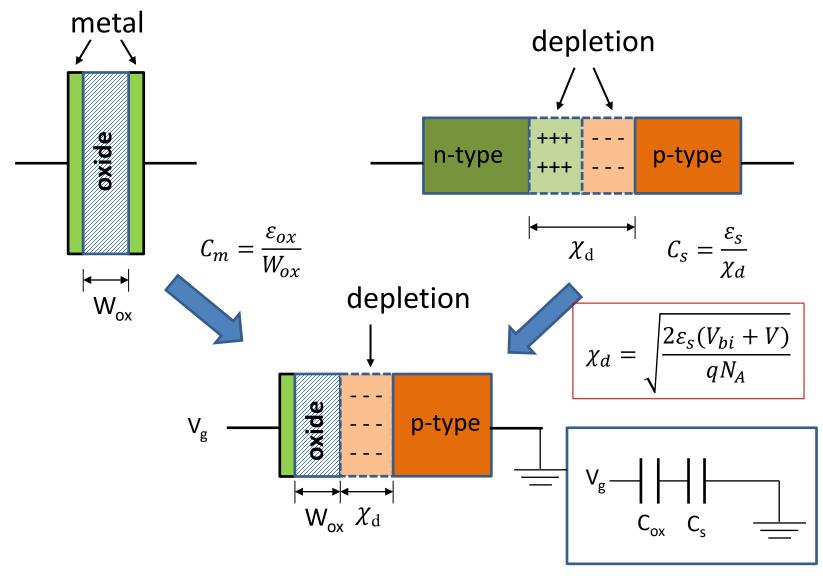
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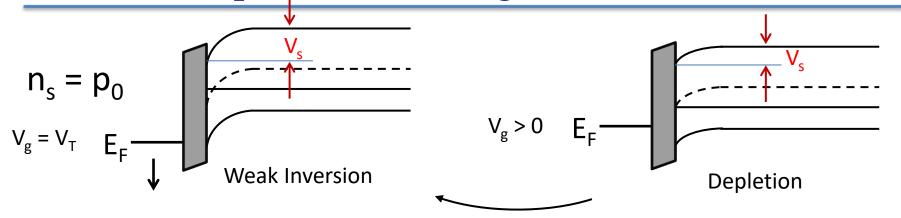
10.3 Non-ideal effects

10.4 The basic MOSFET operation







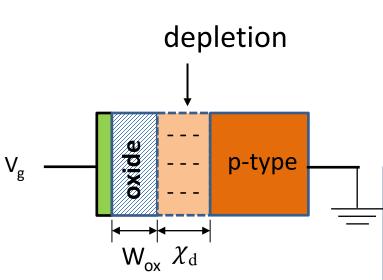


Net charge is zero!

$$(V_g - V_s)C_{ox} = V_sC_s$$

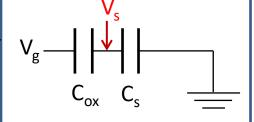
$$V_g C_{ox} = V_s C_{ox} + V_s C_s$$

$$V_S = \frac{V_g C_{ox}}{C_{ox} + C_S}$$



$$C_S = \frac{\varepsilon_S}{\chi_d}$$

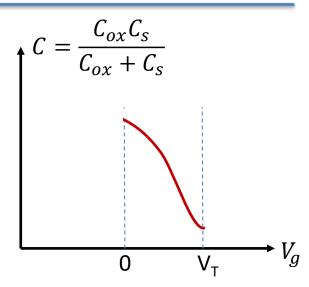
$$\chi_d = \sqrt{\frac{2\varepsilon_s(V_{bi} + V)}{qN_A}}$$





$$V_{S} = \frac{V_{g}C_{ox}}{C_{ox} + C_{s}}$$

$$C_{S} = \frac{\varepsilon_{S}}{\sqrt{\frac{2\varepsilon_{S}(V_{S})}{qN_{A}}}}$$

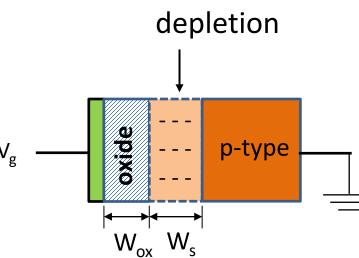


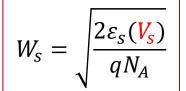
Net charge is zero!

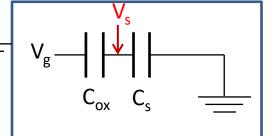
$$(V_g - V_s)C_{ox} = V_sC_s$$

$$V_g C_{ox} = V_s C_{ox} + V_s C_s$$

$$V_S = \frac{V_g C_{ox}}{C_{ox} + C_S}$$

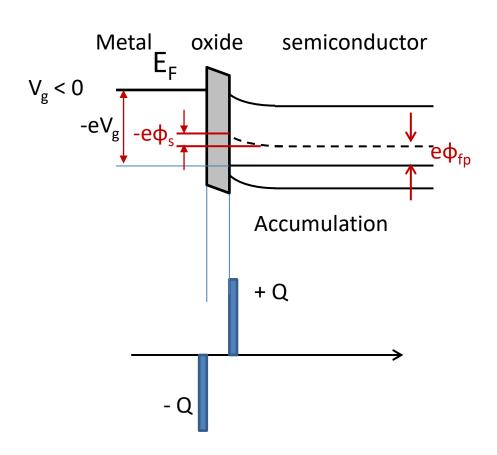


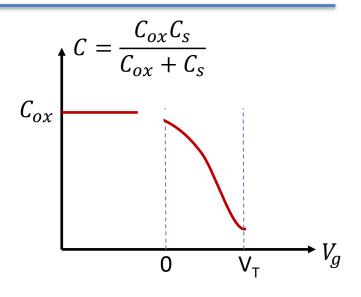






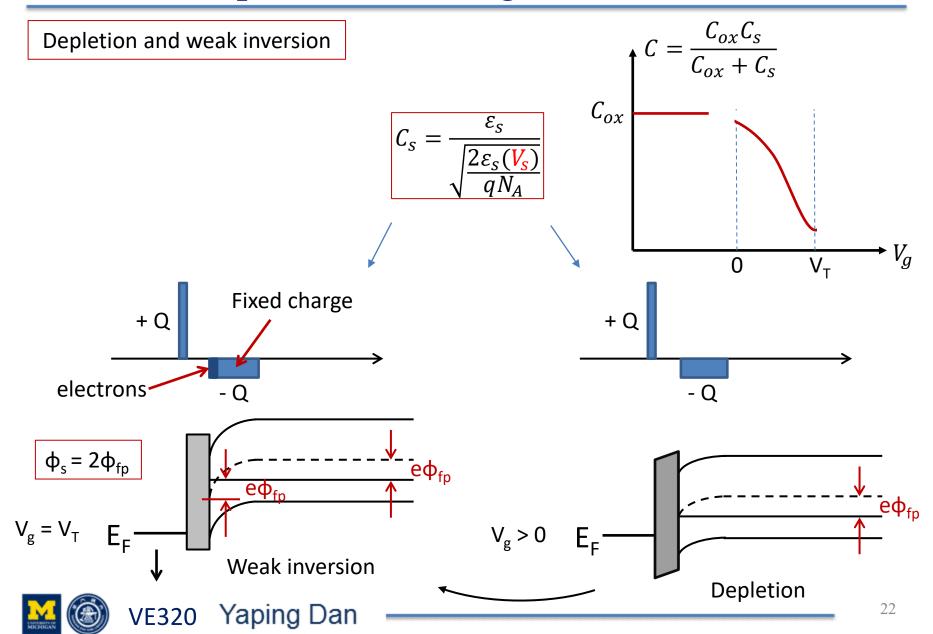
Accumulation

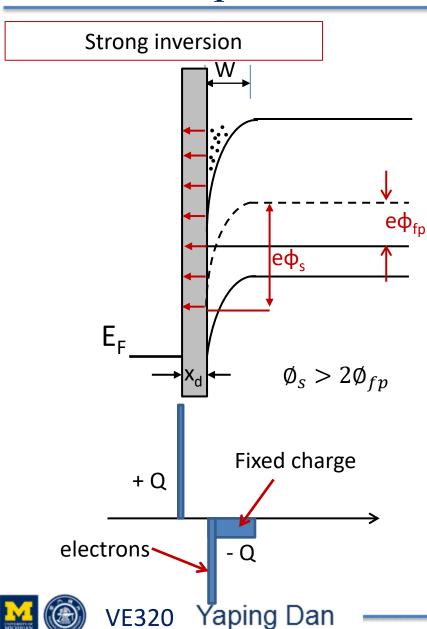


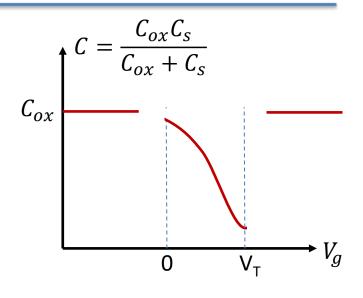


$$C_S \rightarrow \infty$$

$$C = \frac{C_s C_{ox}}{C_s + C_{ox}} \approx C_{ox}$$

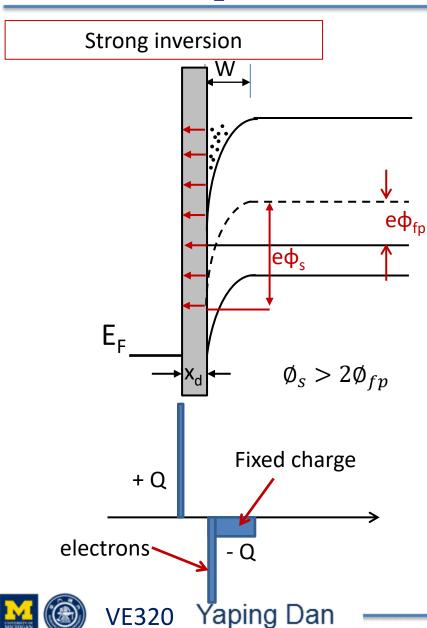


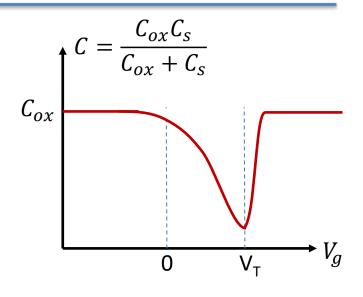




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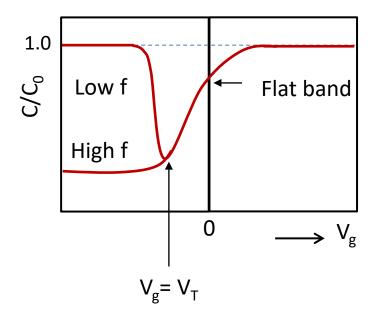


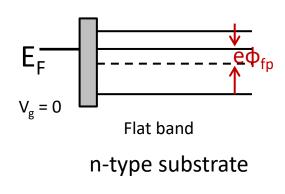


$$C_s \rightarrow \infty$$

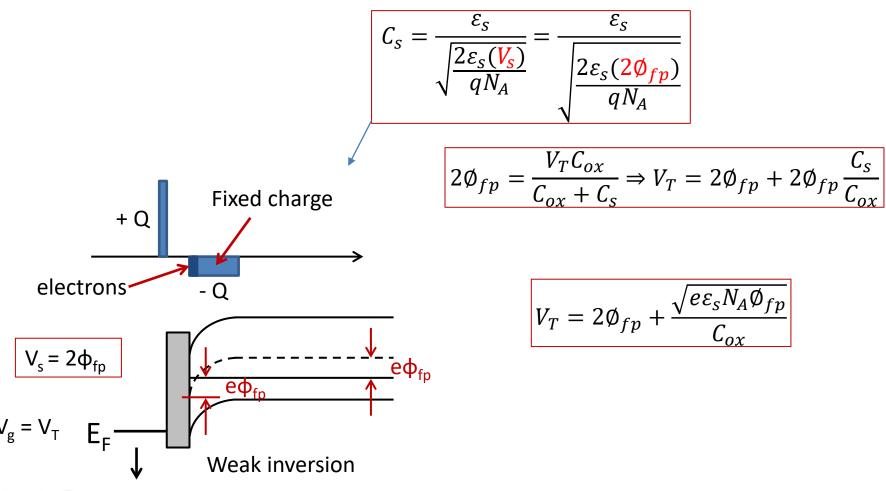
$$C = \frac{C_s C_{ox}}{C_s + C_{ox}} \approx C_{ox}$$

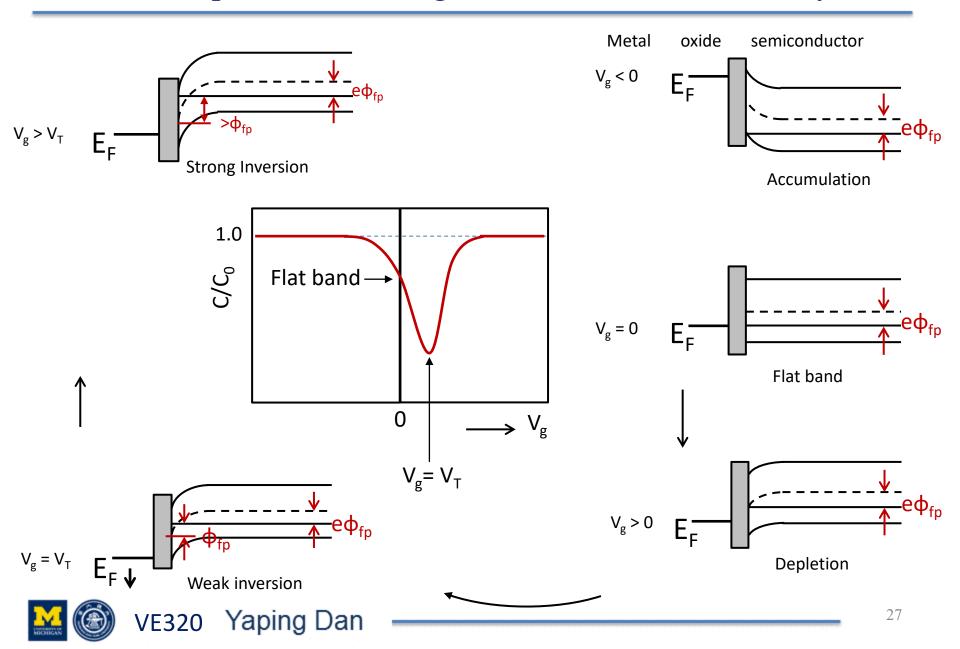
n-type semiconductor

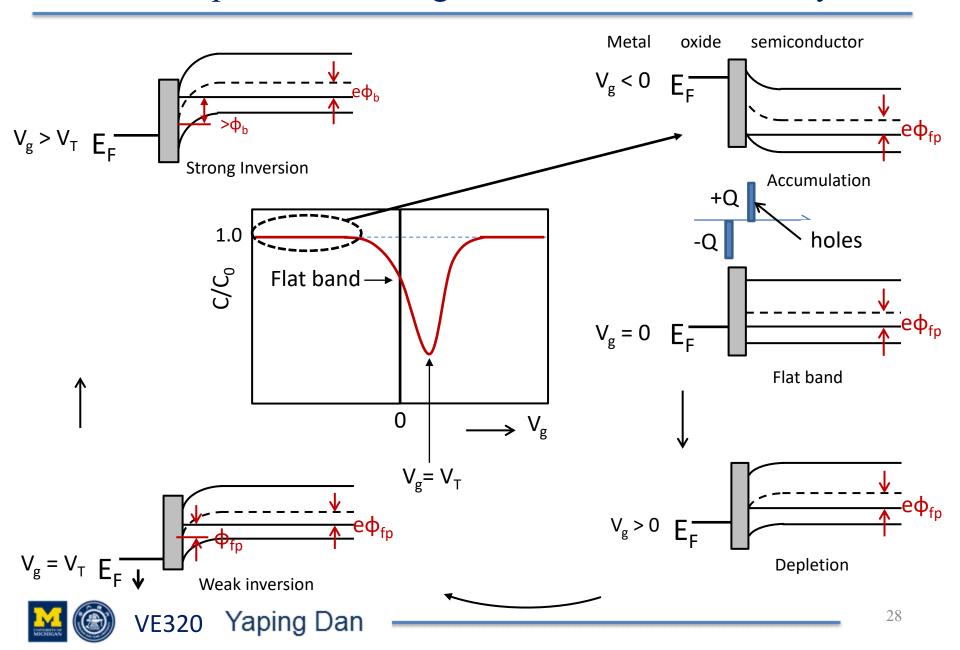


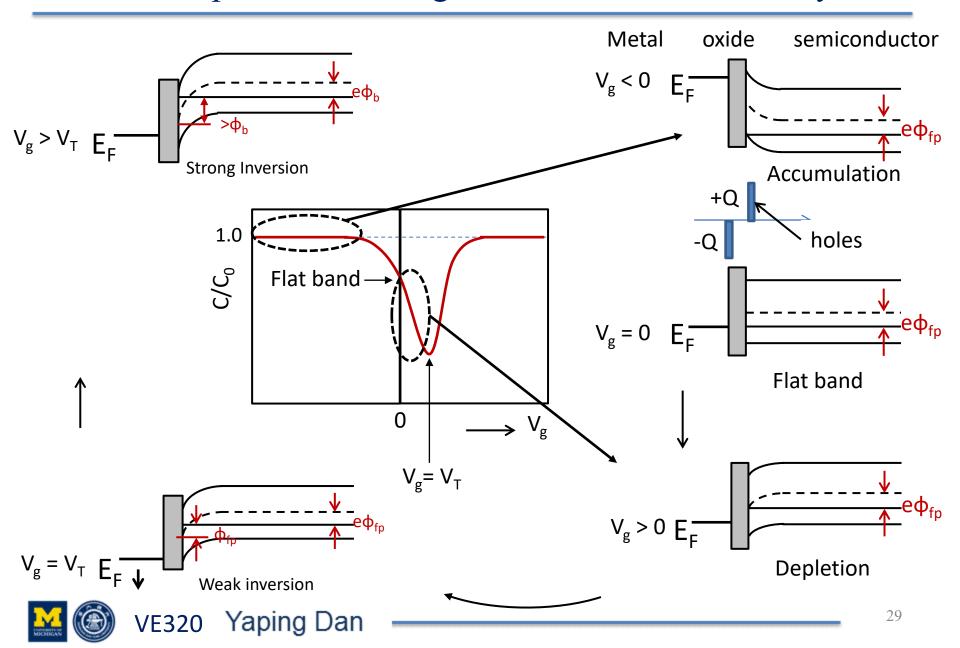


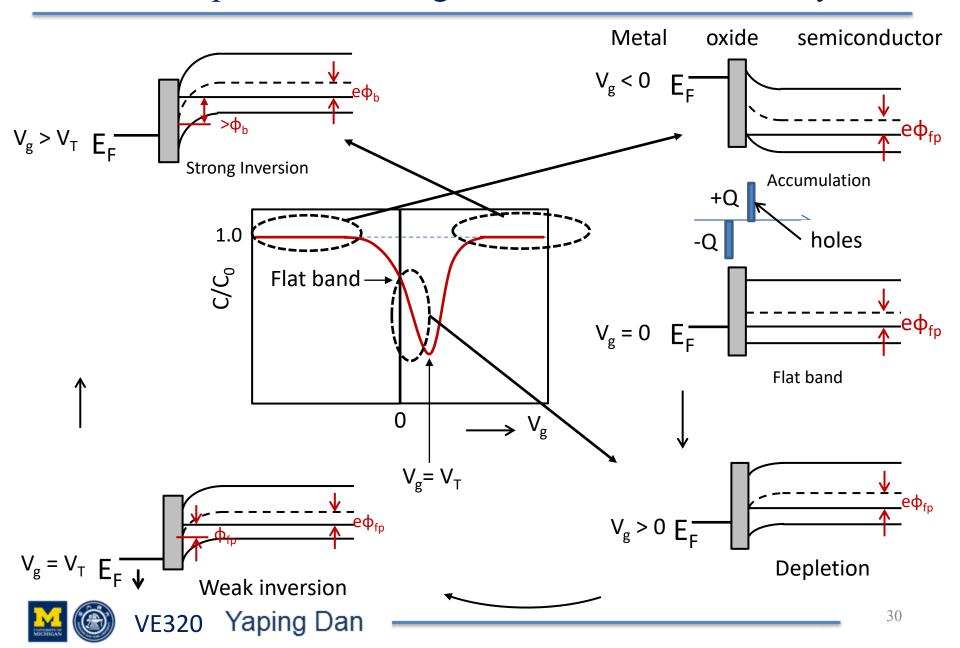
Threshold voltage





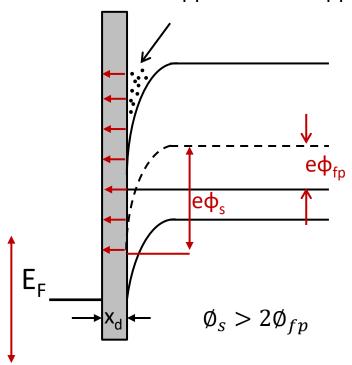






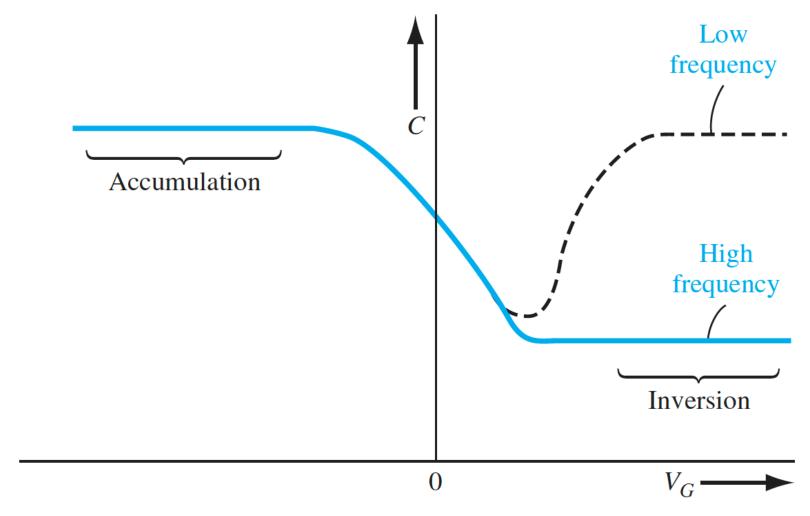
Question:

Appear and disappear

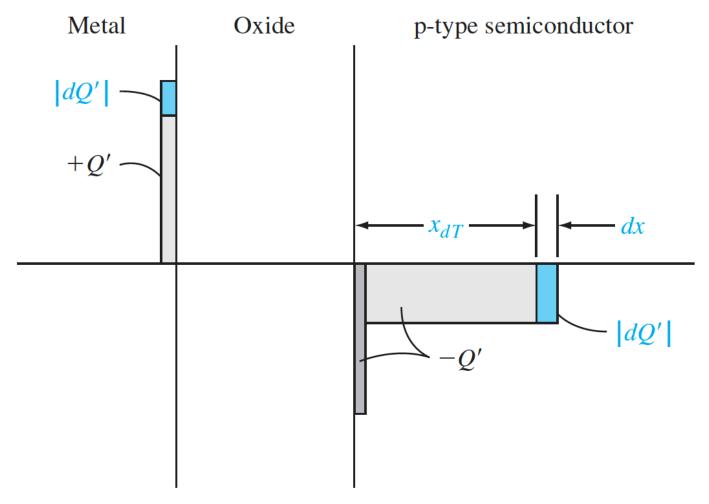


Where are the electrons coming from and going to?

Frequency dependence



Frequency dependence



Outline

10.1 The two-terminal MOS structure

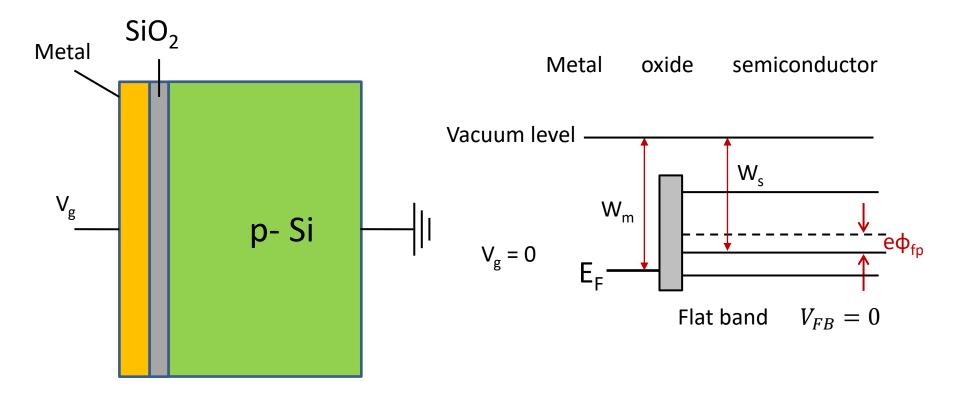
10.2 Capacitance-voltage characteristics

10.3 Non-ideal effects

10.4 The basic MOSFET operation

10.3 Non-ideal effects

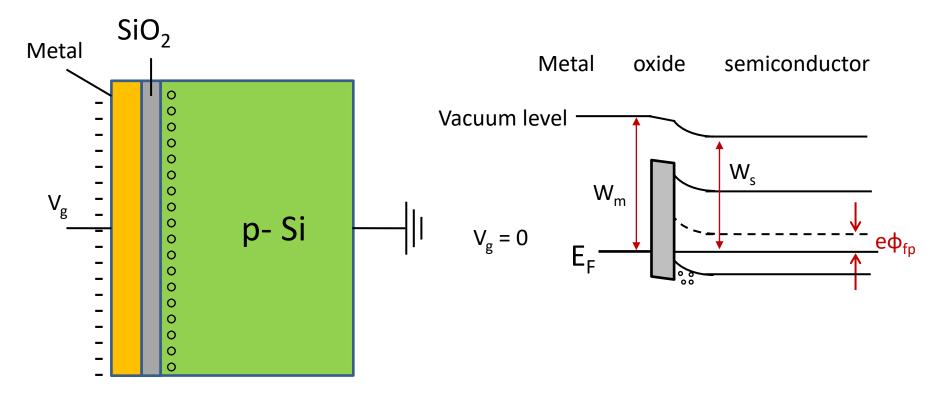
Work function difference



Metal-insulator-semiconductor (MIS)

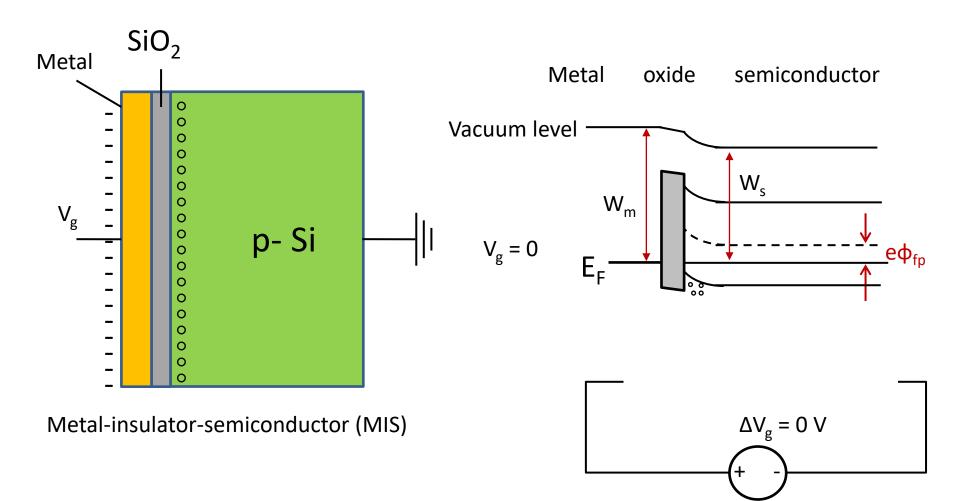
10.3 Non-ideal effects

Work function difference

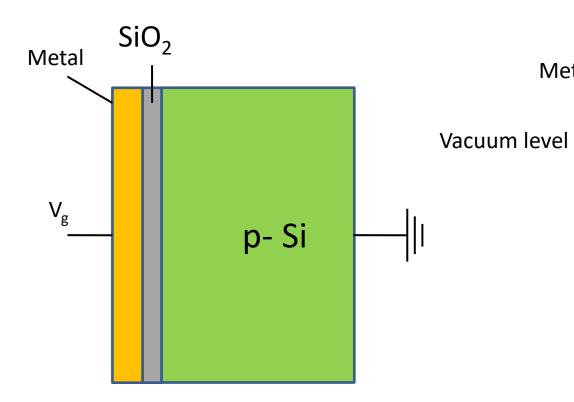


Metal-insulator-semiconductor (MIS)

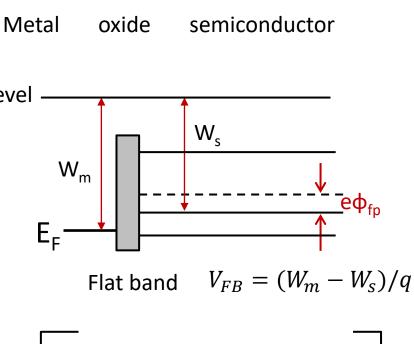
Work function difference

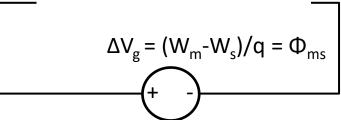


Work function difference

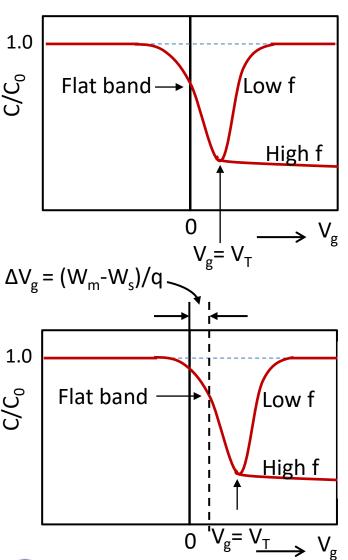


Metal-insulator-semiconductor (MIS)



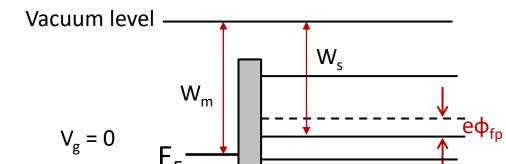




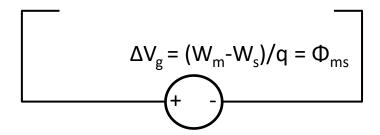


Work function difference

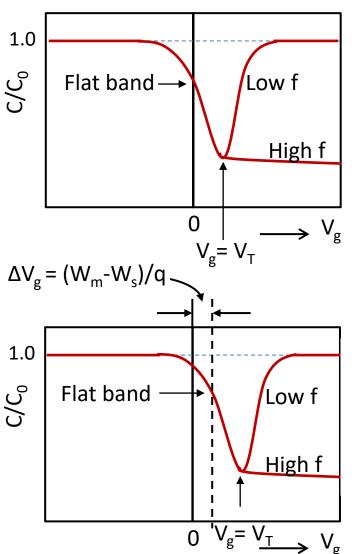
Metal oxide semiconductor



 $V_{FB} = (W_m - W_S)/q$ Flat band





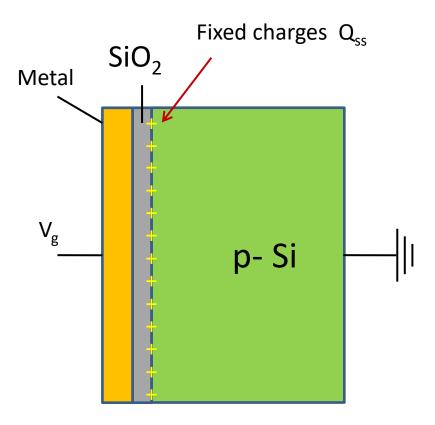


Work function difference

$$V_T = 2\phi_{fp} + t_{ox} \sqrt{\frac{4eN_a \varepsilon_{Si} \phi_{fp}}{\varepsilon_{ox}^2}} = 2\phi_b + \frac{|Q_{SD}|}{C_{ox}}$$

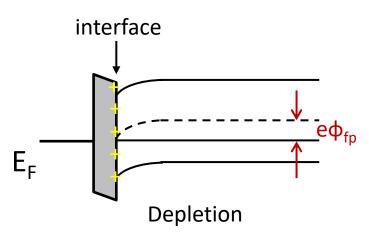
$$V_T = 2\phi_{fp} + t_{ox} \sqrt{\frac{4eN_a \varepsilon_{Si} \phi_{fp}}{\varepsilon_{ox}^2}} + V_{FB}$$
$$= 2\phi_{fp} + \frac{|Q_{SD}|}{C_{ox}} + \phi_{ms}$$

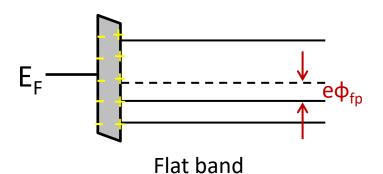
Fixed charges



Metal-insulator-semiconductor (MIS)

Metal oxide semiconductor

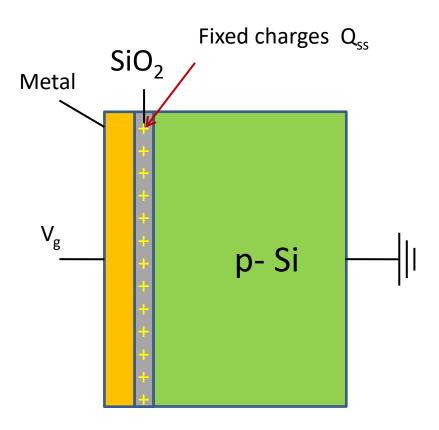




$$V_g = V_{FB} = -Q_{SS}/C$$

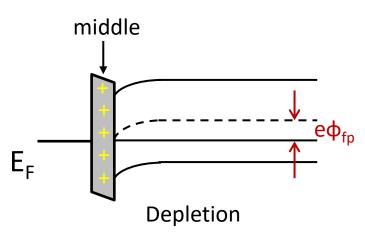


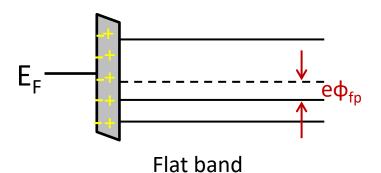
Fixed charges



Metal-insulator-semiconductor (MIS)

Metal oxide semiconductor



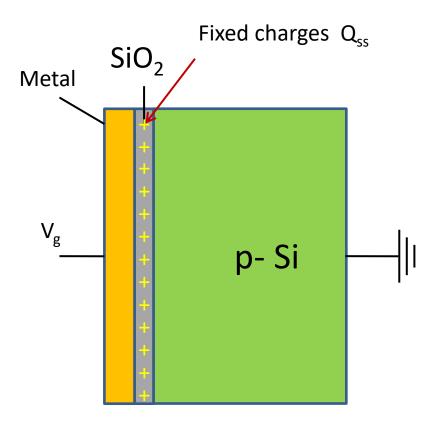


$$V_g = V_{FB} = -Q_{SS}/2C$$



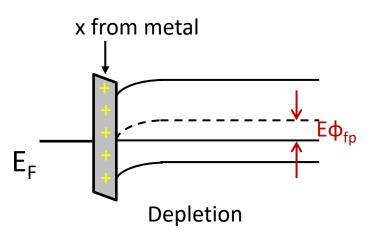


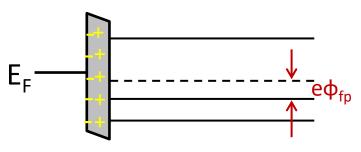
Fixed charges



Metal-insulator-semiconductor (MIS)

Metal oxide semiconductor





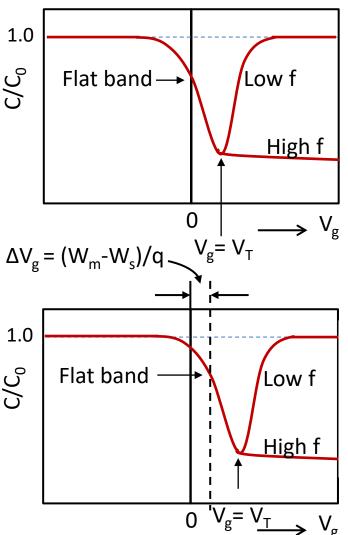
Flat band

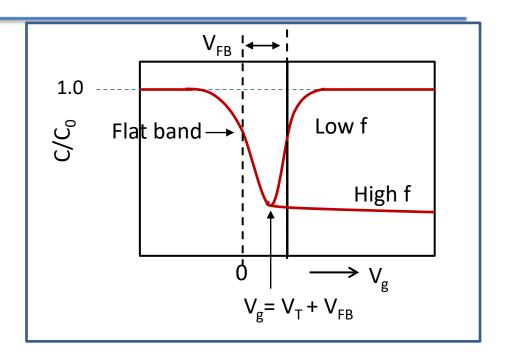
$$V_g = V_{FB} = -\frac{Q_{SS}}{C} \cdot \frac{x}{d}$$



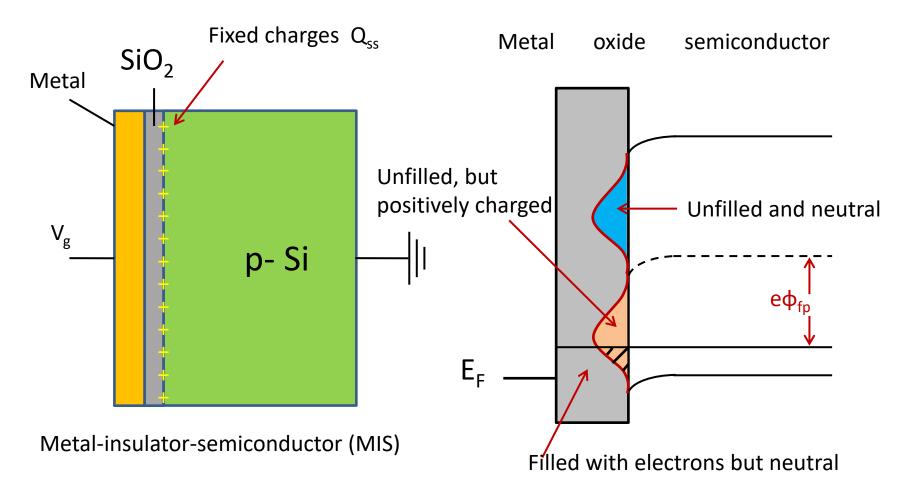


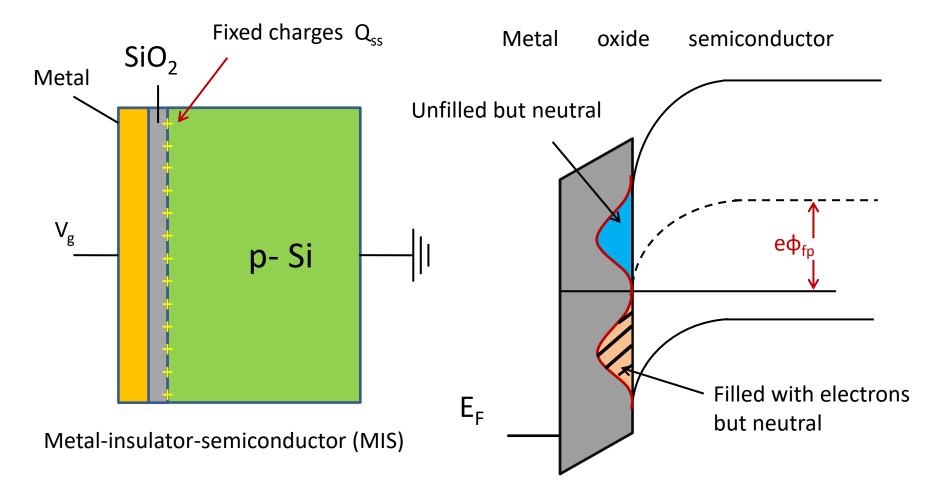
Fixed charges



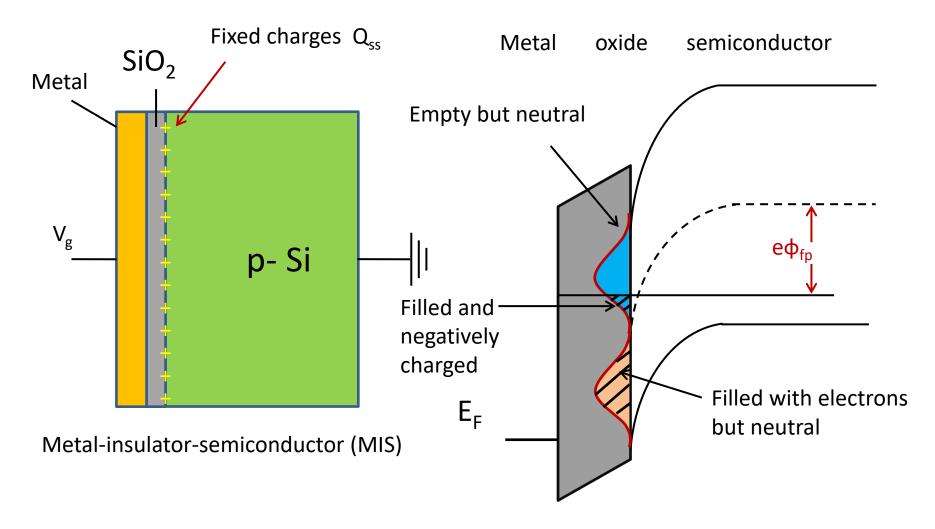


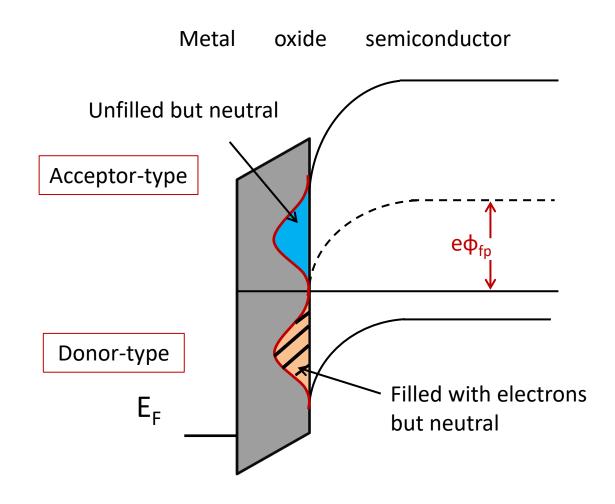
$$V_T = 2\phi_{fp} + t_{ox} \sqrt{\frac{4eN_a \varepsilon_{Si} \phi_{fp}}{\varepsilon_{ox}^2}} + V_{FB}$$
$$= 2\phi_{fp} + \frac{|Q_{SD}|}{C_{ox}} + \phi_{ms} - \frac{Q_{ss}}{C_{ox}}$$

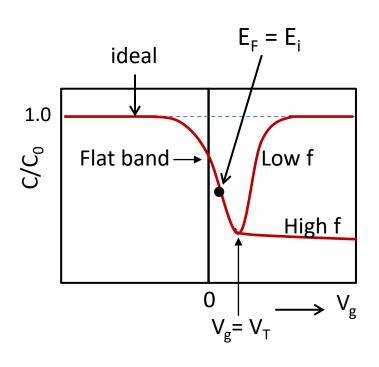


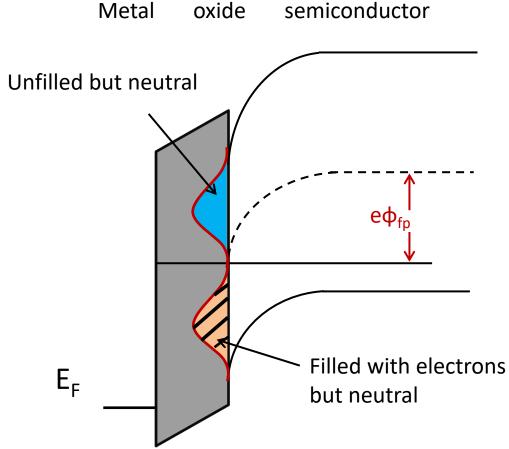


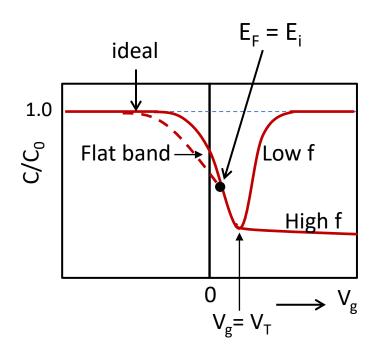


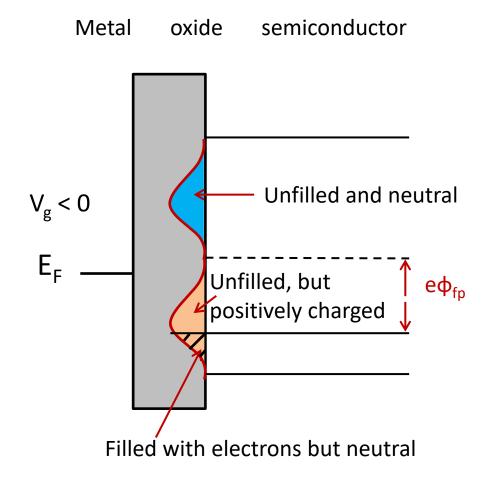


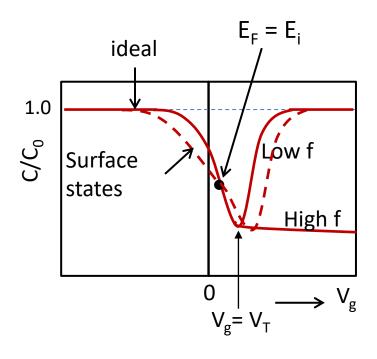


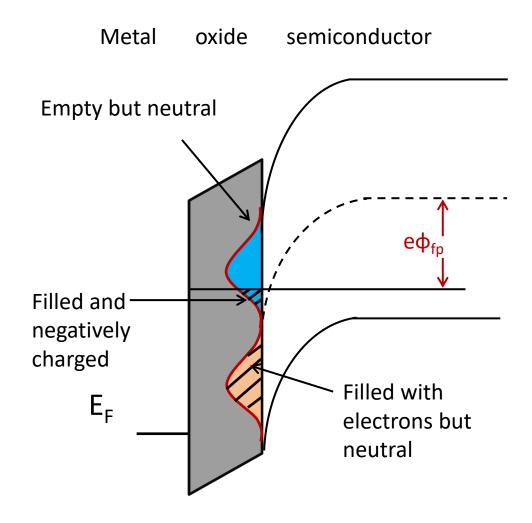








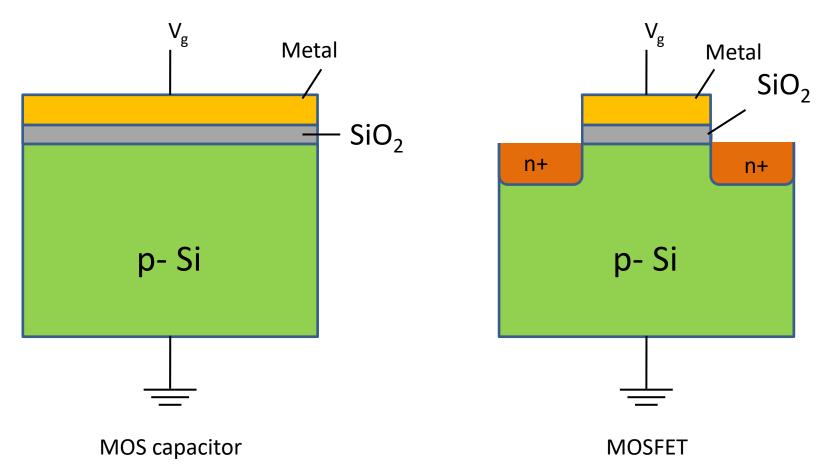




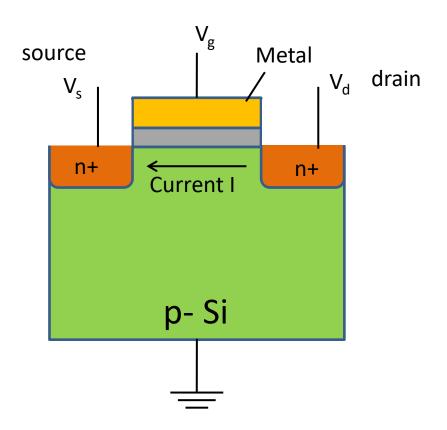
Outline

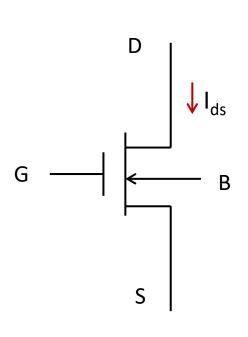
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Metal-Oxide-Semiconductor field effect transistor: MOSFET



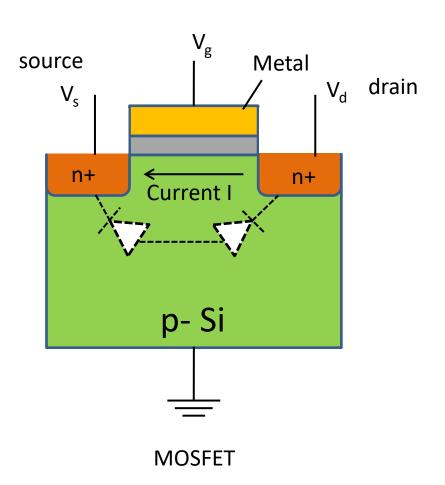
Metal-Oxide-Semiconductor field effect transistor: MOSFET

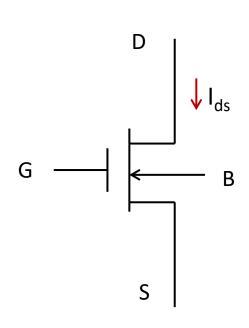




Metal-oxide-semiconductor (MOS)

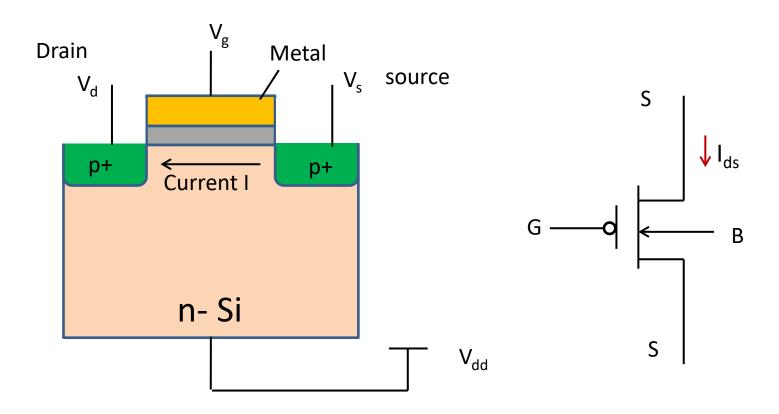
Metal-Oxide-Semiconductor field effect transistor: MOSFET





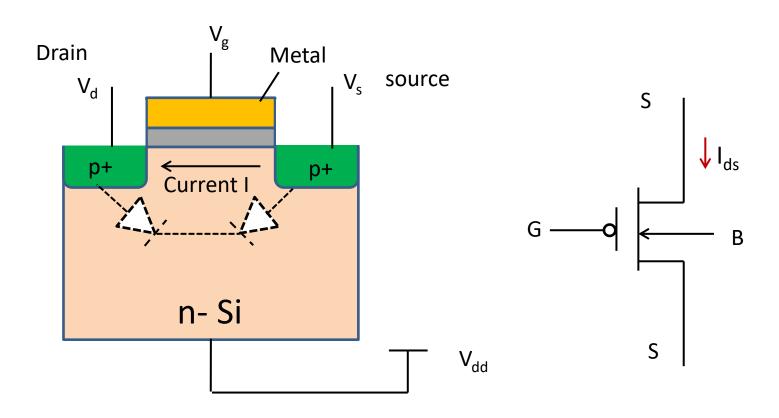


Metal-Oxide-Semiconductor field effect transistor: p-type MOSFET



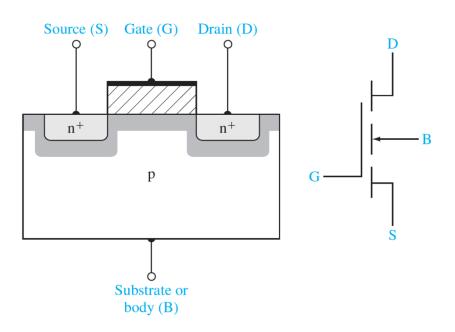
P-type MOSFET

Metal-Oxide-Semiconductor field effect transistor: P MOSFET



P-type MOSFET

MOSFET structures



Source (S) Gate (G) Drain (D)

n+

n+

n+

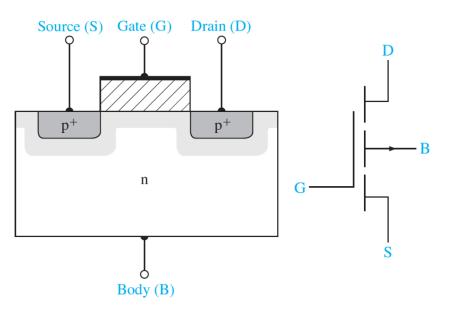
n
g

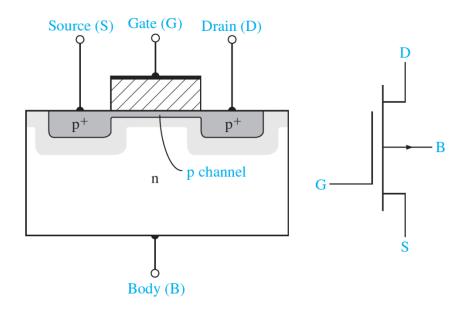
Body (B)

NMOS Enhancement mode

NMOS Depletion mode

MOSFET structures

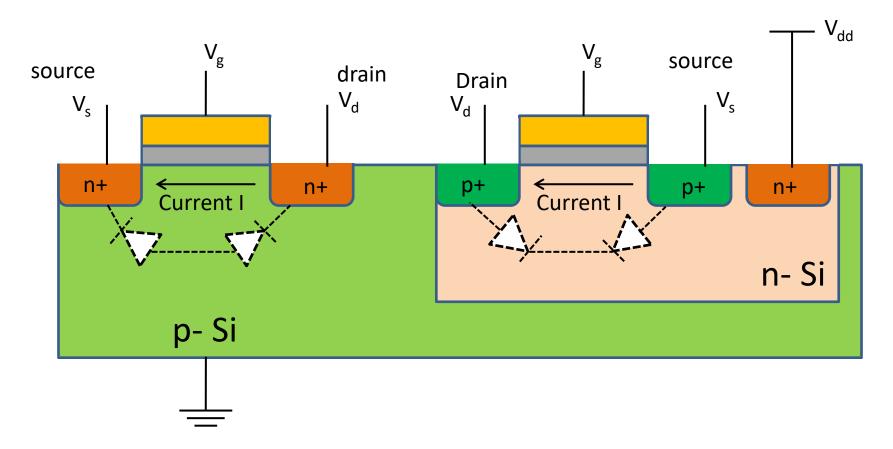




PMOS Enhancement mode

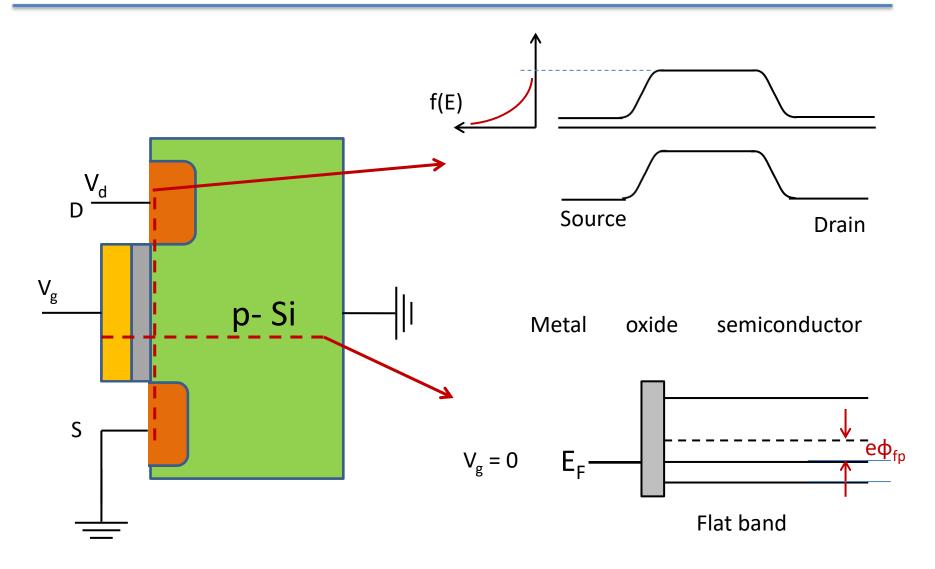
PMOS Depletion mode

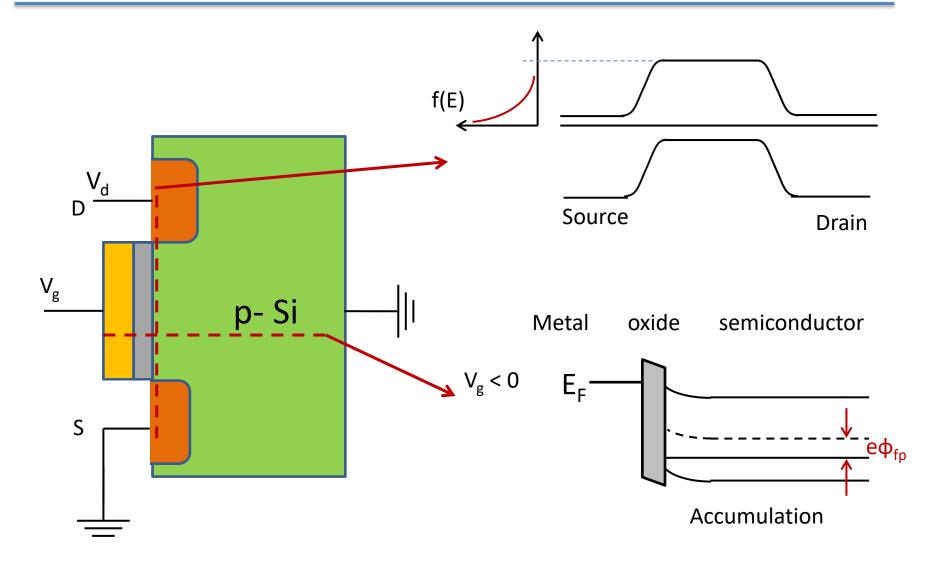
Metal-Oxide-Semiconductor field effect transistor: CMOS



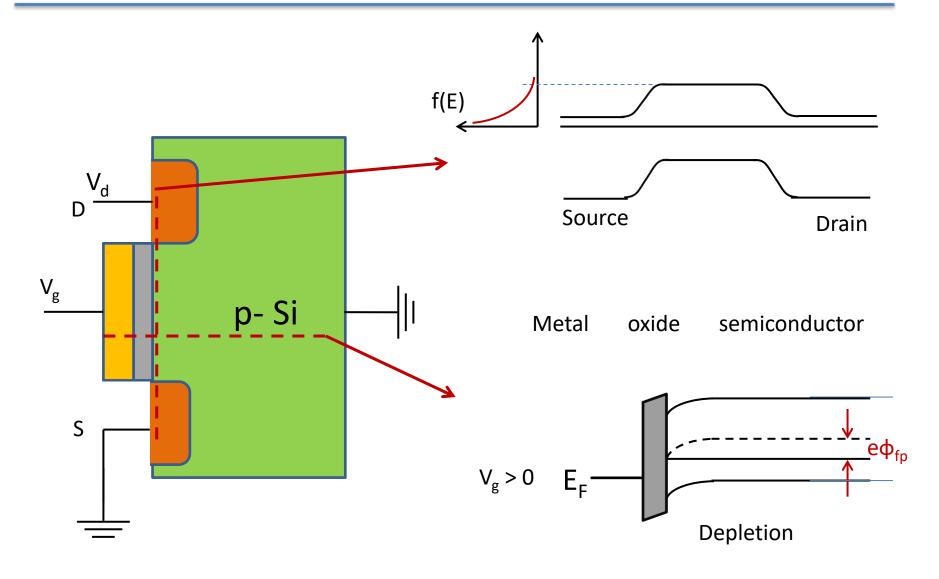
Complementary Metal-oxide-semiconductor (CMOS) field effect transistors



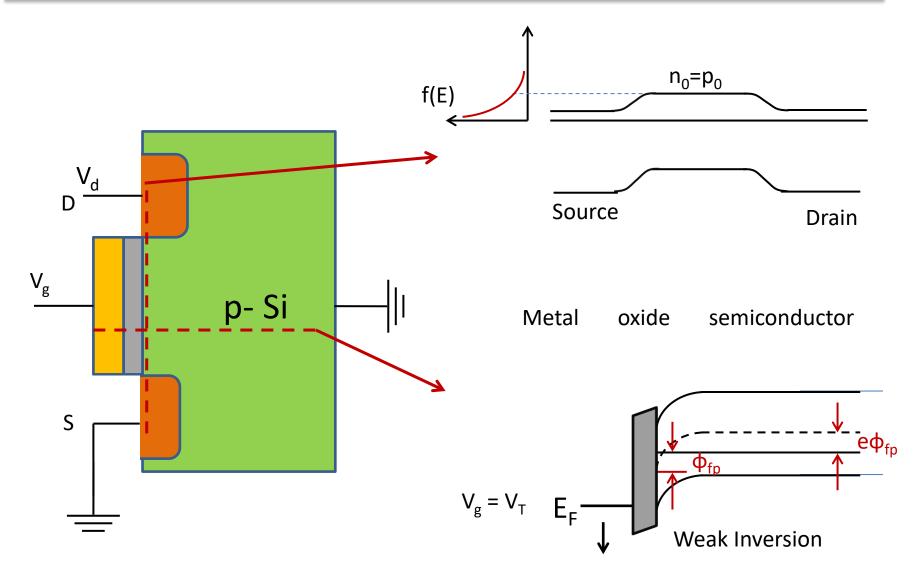


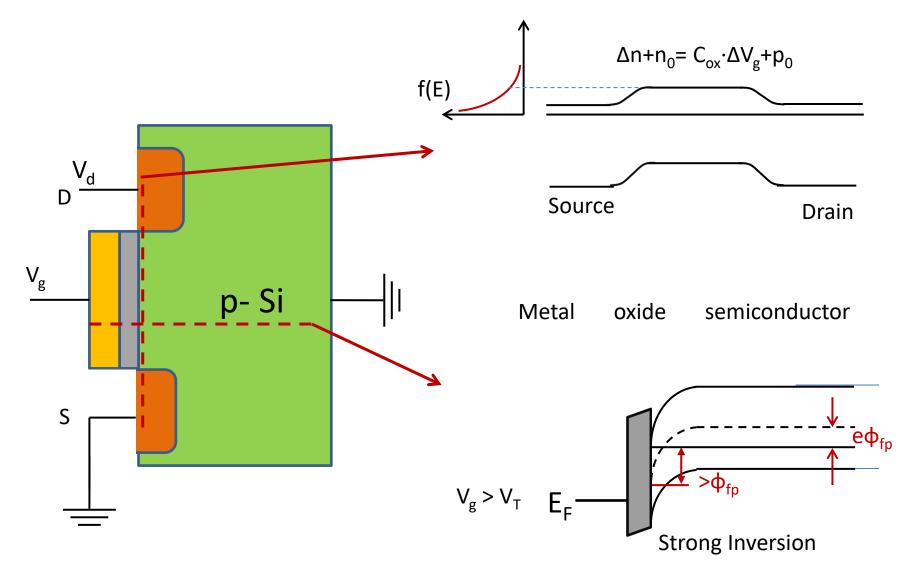






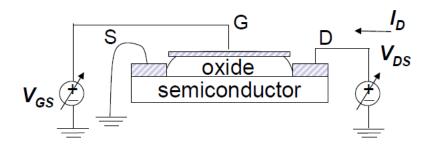


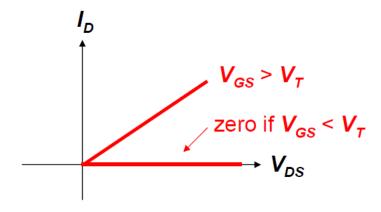




NMOSFET I_D vs. V_{DS} Characteristics

Next consider I_D (flowing into \overline{D}) versus V_{DS} , as V_{GS} is varied:





Above threshold (V_{GS} > V_T): "inversion layer" of electrons appears, so conduction between **S** and **D** is possible

Below "threshold" ($V_{GS} < V_T$): no charge \rightarrow no conduction

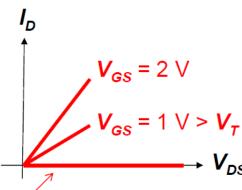
Current-voltage characteristics

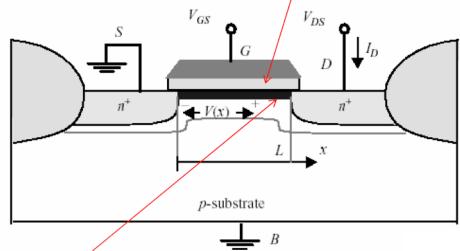
The MOSFET as a Controlled Resistor

- The MOSFET behaves as a resistor when V_{DS} is low:
 - \square Drain current I_D increases linearly with V_{DS}
 - \square Resistance R_{DS} between SOURCE & DRAIN depends on V_{GS}

• R_{DS} is lowered as V_{GS} increases above V_T

NMOSFET Example:





oxide thickness $\equiv t_{ox}$

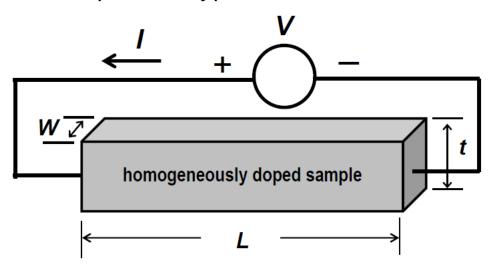
Inversion charge density $Q_{i}(x) = -C_{ox}[V_{GS}-V_{T}-V(x)]$ $I_{DS} = 0$ if $V_{GS} < V_{T}$ where $C_{ox} \equiv \varepsilon_{ox} / t_{ox}$



Current-voltage characteristics

Sheet Resistance Revisited

Consider a sample of n-type semiconductor:



$$R_{s} = \frac{\rho}{t} = \frac{1}{\sigma t} = \frac{1}{q\mu_{n}nt} = \frac{1}{\mu_{n}Q_{n}}$$

where Q_n is the charge per unit area

MOSFET as a Controlled Resistor (cont'd)

$$I_D = \frac{V_{DS}}{R_{DS}}$$

$$R_{DS} = R_s(L/W) = \frac{L/W}{\mu_n Q_i} = \frac{L/W}{\mu_n C_{ox}(V_{GS} - V_T - \frac{V_{DS}}{2})}$$

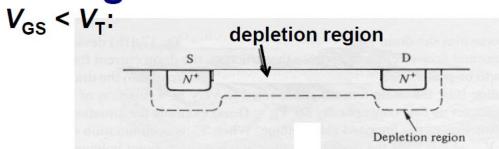
$$I_{D} = \mu_{n} C_{ox} \frac{W}{L} (V_{GS} - V_{T} - \frac{V_{DS}}{2}) V_{DS}$$

average value of V(x)

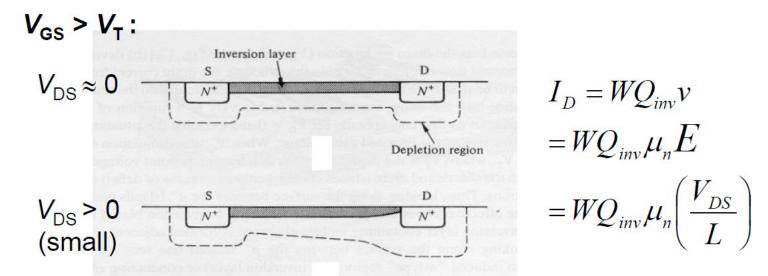
We can make R_{DS} low by

- applying a large "gate drive" $(V_{GS} V_T)$
- making W large and/or L small

Charge in an N-Channel MOSFET

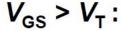


(no inversion layer at surface)



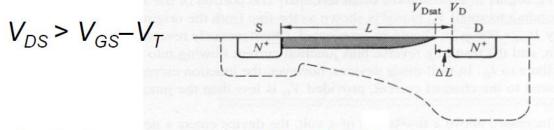
Average electron velocity **v** is proportional to lateral electric field **E**

What Happens at Larger V_{DS} ?



$$V_{DS} = V_{GS} - V_T$$
 s D N+

Inversion-layer is "pinched-off" at the drain end



As V_{DS} increases above $V_{GS} - V_T \equiv V_{DSAT}$,

the length of the "pinch-off" region ΔL increases:

- "extra" voltage $(V_{DS} V_{Dsat})$ is dropped across the distance ΔL
- ullet the voltage dropped across the inversion-layer "resistor" remains $oldsymbol{V_{Dsat}}$

 \Rightarrow the drain current I_D saturates

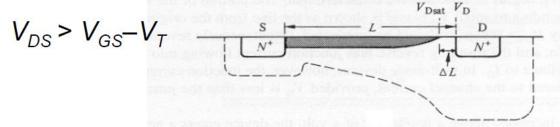
Note: Electrons are swept into the drain by the E-field when they enter the pinch-off region.

What Happens at Larger V_{DS} ?

 $V_{\rm GS} > V_{\rm T}$:

$$V_{DS} = V_{GS} - V_T$$
 s D N+

Inversion-layer is "pinched-off" at the drain end



As V_{DS} increases above $V_{GS} - V_T \equiv V_{DSAT}$

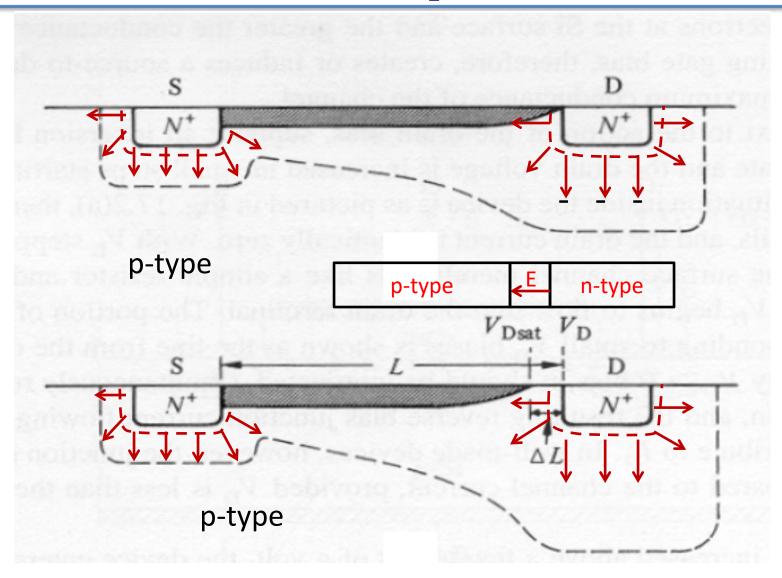
$$I_D = \mu_n C_{ox} \frac{W}{L} \left(V_{GS} - V_T - \frac{1}{2} V_{DS} \right) V_{DS}$$
 I_D will not increase after $V_{DS} \ge V_{GS} - V_T$

$$I_D = \mu_n C_{ox} \frac{W}{L} \left(V_{GS} - V_T - \frac{1}{2} V_{DS} \right) V_{DS} = \frac{1}{2} \mu_n C_{ox} \frac{W}{L} (V_{GS} - V_T) (V_{GS} - V_T)$$

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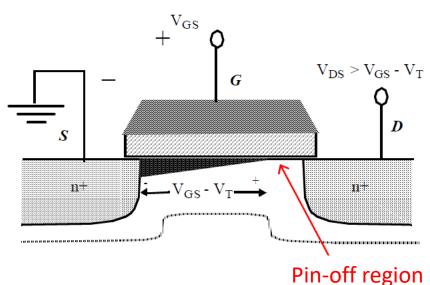
Instructor: Octavian Florescu





Summary of I_D vs. V_{DS}

- As V_{DS} increases, the inversion-layer charge density at the drain end of the channel is reduced; therefore, I_D does not increase linearly with V_{DS} .
- When V_{DS} reaches $V_{GS} V_T$, the channel is "pinched off" at the drain end, and I_D saturates (i.e. it does not increase with further increases in V_{DS}).



$$I_{DSAT} = \mu_n C_{ox} \frac{W}{2L} (V_{GS} - V_T)^2$$



I_D vs. V_{DS} Characteristics

The MOSFET I_D - V_{DS} curve consists of two regions:

1) Resistive or "Triode" Region: $0 < V_{DS} < V_{GS} - V_{T}$

$$I_D = k_n' \frac{W}{L} \left[V_{GS} - V_T - \frac{V_{DS}}{2} \right] V_{DS}$$
 where $k_n' = \mu_n C_{ox}$

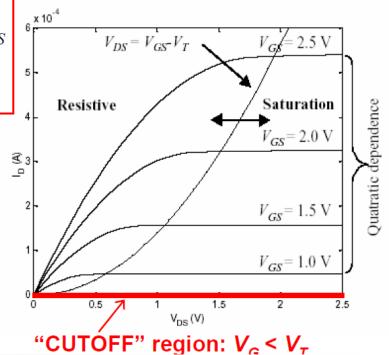
process transconductance parameter

2) Saturation Region:

$$V_{DS} > V_{GS} - V_{T}$$

$$I_{DSAT} = \frac{k_n'}{2} \frac{W}{L} (V_{GS} - V_T)^2$$

where
$$k'_n = \mu_n C_{ox}$$



$$I_{D} = \frac{W\mu_{n} C_{\text{ox}}}{L} (V_{GS} - V_{T}) V_{DS}$$

$$\sqrt{I_{D}(\text{sat})} = \sqrt{\frac{W\mu_{n} C_{\text{ox}}}{2L}} (V_{GS} - V_{T})$$

$$Very \text{ small } V_{DS}$$

$$\int_{I_{D}} B A$$

$$Slope = \sqrt{\frac{\mu C_{\text{ox}} W V_{DS}}{2L}}$$

$$V_{T} V_{GS} \longrightarrow V_{TA} V_{GS} \longrightarrow V_{TA}$$
(a) (b)



Transconductance:
$$g_m = \frac{\partial I_D}{\partial V_{GS}}$$

$$I_D = k_n' \frac{W}{L} \left[V_{GS} - V_T - \frac{V_{DS}}{2} \right] V_{DS} \qquad g_{mL} = \frac{\partial I_D}{\partial V_{GS}} = \frac{W \mu_n C_{\text{ox}}}{L} \cdot V_{DS}$$

$$g_{mL} = \frac{\partial I_D}{\partial V_{GS}} = \frac{W \mu_n C_{\text{ox}}}{L} \cdot V_{DS}$$

 $0 < V_{\text{DS}} < V_{\text{GS}} - V_{\text{T}}$

$$I_{DSAT} = \frac{k_n'}{2} \frac{W}{L} (V_{GS} - V_T)^2$$

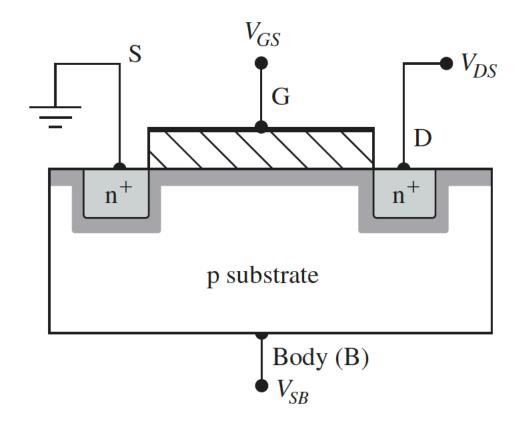
$$g_{ms} = \frac{\partial I_D(\text{sat})}{\partial V_{GS}} = \frac{W\mu_n C_{\text{ox}}}{L} (V_{GS} - V_T)$$

$$V_{DS} > V_{GS} - V_{T}$$

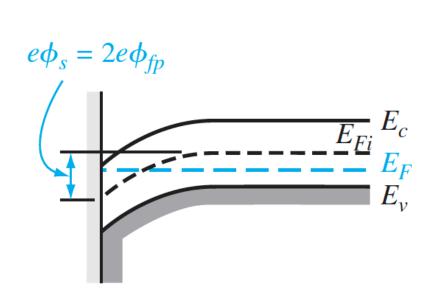


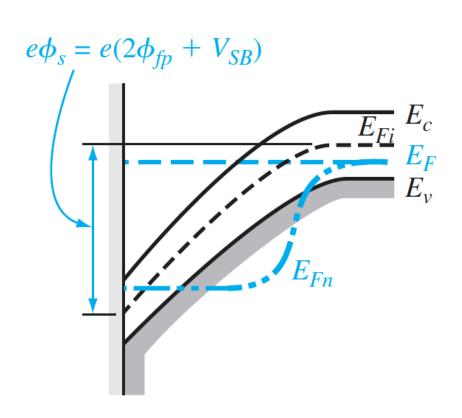


Substrate bias effect



Substrate bias effect





Substrate bias effect

When $V_{SB} = 0$, we had

$$Q'_{SD}$$
 (max) = $-eN_a x_{dT} = -\sqrt{2e\epsilon_s N_a(2\phi_{fp})}$

When $V_{SB} > 0$, the space charge width increases and we now have

$$Q'_{SD} = -eN_a x_d = -\sqrt{2e\epsilon_s N_a(2\phi_{fp} + V_{SB})}$$

The change in the space charge density is then

$$\Delta Q_{SD}' = -\sqrt{2e\epsilon_s N_a} \left[\sqrt{2\phi_{fp} + V_{SB}} - \sqrt{2\phi_{fp}} \right]$$

Substrate bias effect

$$\Delta V_T = -\frac{\Delta Q_{SD}'}{C_{\text{ox}}} = \frac{\sqrt{2e\epsilon_s N_a}}{C_{\text{ox}}} \left[\sqrt{2\phi_{fp} + V_{SB}} - \sqrt{2\phi_{fp}} \right]$$

$$\gamma = \frac{\sqrt{2e\epsilon_s N_a}}{C_{or}}$$

$$\Delta V_T = \gamma \left[\sqrt{2\phi_{fp} + V_{SB}} - \sqrt{2\phi_{fp}} \right]$$